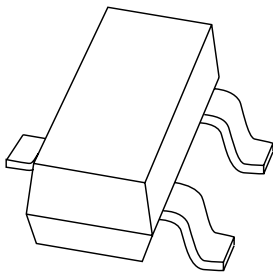


# DATA SHEET



**BF824**

PNP medium frequency transistor

Product data sheet  
Supersedes data of 1999 Apr 15

2004 Jan 16

## PNP medium frequency transistor

BF824

## FEATURES

- Low current (max. 25 mA)
- Low voltage (max. 30 V).

## APPLICATIONS

- RF stages in FM front-ends in common base configuration.

## DESCRIPTION

PNP medium frequency transistor in a SOT23 plastic package.

## MARKING

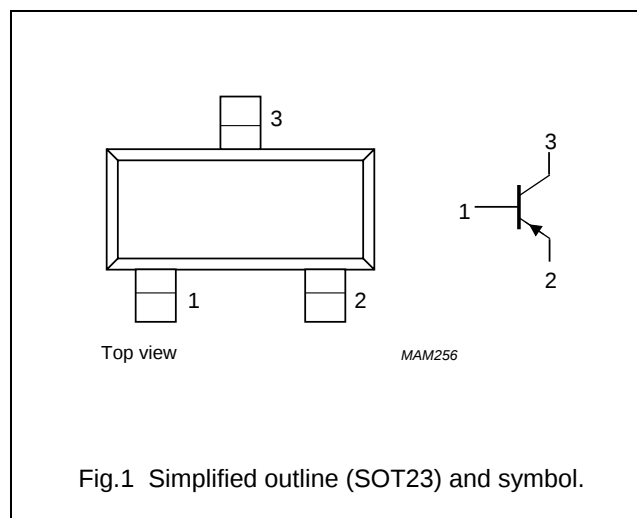
| TYPE NUMBER | MARKING CODE <sup>(1)</sup> |
|-------------|-----------------------------|
| BF824       | F8*                         |

## Note

- \* = p : Made in Hong Kong.  
 \* = t : Made in Malaysia.  
 \* = W : Made in China.

## PINNING

| PIN | DESCRIPTION |
|-----|-------------|
| 1   | base        |
| 2   | emitter     |
| 3   | collector   |



## ORDERING INFORMATION

| TYPE NUMBER | PACKAGE |                                          |         |
|-------------|---------|------------------------------------------|---------|
|             | NAME    | DESCRIPTION                              | VERSION |
| BF824       | –       | plastic surface mounted package; 3 leads | SOT23   |

## PNP medium frequency transistor

BF824

## LIMITING VALUES

In accordance with the Absolute Maximum Rating System (IEC 60134).

| SYMBOL    | PARAMETER                     | CONDITIONS                           | MIN. | MAX. | UNIT |
|-----------|-------------------------------|--------------------------------------|------|------|------|
| $V_{CBO}$ | collector-base voltage        | open emitter                         | –    | –30  | V    |
| $V_{CEO}$ | collector-emitter voltage     | open base                            | –    | –30  | V    |
| $V_{EBO}$ | emitter-base voltage          | open collector                       | –    | –4   | V    |
| $I_C$     | collector current (DC)        |                                      | –    | –25  | mA   |
| $I_{CM}$  | peak collector current        |                                      | –    | –25  | mA   |
| $P_{tot}$ | total power dissipation       | $T_{amb} \leq 25\text{ °C}$ ; note 1 | –    | 250  | mW   |
| $T_{stg}$ | storage temperature           |                                      | –65  | +150 | °C   |
| $T_j$     | junction temperature          |                                      | –    | 150  | °C   |
| $T_{amb}$ | operating ambient temperature |                                      | –65  | +150 | °C   |

## Note

1. Transistor mounted on an FR4 printed-circuit board.

## THERMAL CHARACTERISTICS

| SYMBOL        | PARAMETER                                   | CONDITIONS | VALUE | UNIT |
|---------------|---------------------------------------------|------------|-------|------|
| $R_{th(j-a)}$ | thermal resistance from junction to ambient | note 1     | 500   | K/W  |

## Note

1. Transistor mounted on an FR4 printed-circuit board.

## CHARACTERISTICS

 $T_j = 25\text{ °C}$  unless otherwise specified.

| SYMBOL    | PARAMETER                 | CONDITIONS                                               | MIN. | TYP. | MAX. | UNIT |
|-----------|---------------------------|----------------------------------------------------------|------|------|------|------|
| $I_{CBO}$ | collector cut-off current | $I_E = 0$ ; $V_{CB} = -30\text{ V}$                      | –    | –    | –50  | nA   |
| $I_{EBO}$ | emitter cut-off current   | $I_C = 0$ ; $V_{EB} = -4\text{ V}$                       | –    | –    | –100 | nA   |
| $h_{FE}$  | DC current gain           | $I_C = -1\text{ mA}$ ; $V_{CE} = -10\text{ V}$           | 25   | 45   | –    |      |
|           |                           | $I_C = -4\text{ mA}$ ; $V_{CE} = -10\text{ V}$           | 25   | 50   | –    |      |
| $V_{BE}$  | base-emitter voltage      | $I_C = -4\text{ mA}$ ; $V_{CE} = -10\text{ V}$           | –    | –    | –900 | mV   |
| $C_{re}$  | feedback capacitance      | $I_C = 0$ ; $V_{CE} = -10\text{ V}$ ; $f = 1\text{ MHz}$ | –    | –    | 0.3  | pF   |
| $f_T$     | transition frequency      | $V_{CE} = -10\text{ V}$ ; $f = 100\text{ MHz}$           |      |      |      |      |
|           |                           | $I_C = -1\text{ mA}$                                     | 250  | 350  | –    | MHz  |
|           |                           | $I_C = -4\text{ mA}$                                     | 400  | 450  | –    | MHz  |
|           |                           | $I_C = -8\text{ mA}$                                     | 390  | 440  | –    | MHz  |

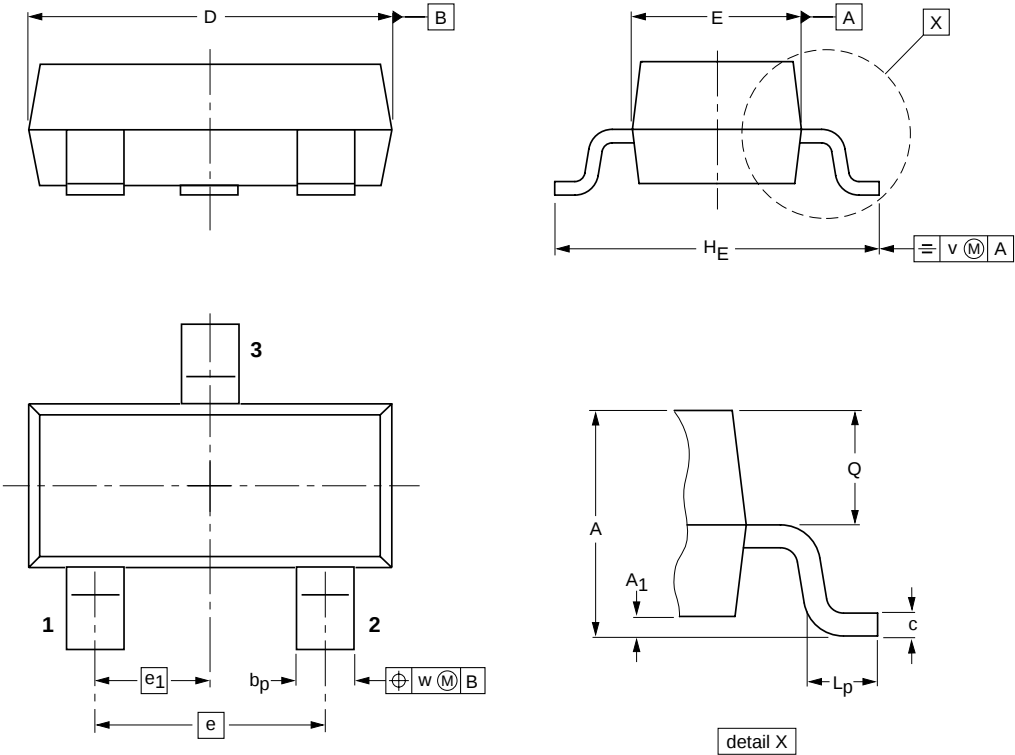
PNP medium frequency transistor

BF824

PACKAGE OUTLINE

Plastic surface-mounted package; 3 leads

SOT23



DIMENSIONS (mm are the original dimensions)

| UNIT | A          | A <sub>1</sub><br>max. | b <sub>p</sub> | c            | D          | E          | e   | e <sub>1</sub> | H <sub>E</sub> | L <sub>p</sub> | Q            | v   | w   |
|------|------------|------------------------|----------------|--------------|------------|------------|-----|----------------|----------------|----------------|--------------|-----|-----|
| mm   | 1.1<br>0.9 | 0.1                    | 0.48<br>0.38   | 0.15<br>0.09 | 3.0<br>2.8 | 1.4<br>1.2 | 1.9 | 0.95           | 2.5<br>2.1     | 0.45<br>0.15   | 0.55<br>0.45 | 0.2 | 0.1 |

| OUTLINE<br>VERSION | REFERENCES |          |       |  | EUROPEAN<br>PROJECTION                                                                | ISSUE DATE           |
|--------------------|------------|----------|-------|--|---------------------------------------------------------------------------------------|----------------------|
|                    | IEC        | JEDEC    | JEITA |  |                                                                                       |                      |
| SOT23              |            | TO-236AB |       |  |  | 04-11-04<br>06-03-16 |

## PNP medium frequency transistor

BF824

## DATA SHEET STATUS

| DOCUMENT STATUS <sup>(1)</sup> | PRODUCT STATUS <sup>(2)</sup> | DEFINITION                                                                            |
|--------------------------------|-------------------------------|---------------------------------------------------------------------------------------|
| Objective data sheet           | Development                   | This document contains data from the objective specification for product development. |
| Preliminary data sheet         | Qualification                 | This document contains data from the preliminary specification.                       |
| Product data sheet             | Production                    | This document contains the product specification.                                     |

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## **Customer notification**

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## **Contact information**

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